ASSOCIATION CONNECTING ELECTRONICS INDUSTRIESS	Composition De t 2005. IPC, Bannock l and Pan-American co	claration burn, Illinois. A opyright conver	ll rights reserved u ntions.	nder both	This docume level parts, t	ent is a declaration entities of the declaration entities	on of the substan	ces within the man ower level material	ufacturer liste s for which the	d item. Note: if e manufacturer	the item is an as has engineering	ssembly with low responsibility.	
				Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information			
upplier Information													
ompany name*	Company uni	Company unique ID			Unique ID Authority				Response Date*				
nsemi									2024-04-27				
Contact Name Titl			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Tit			Title - Representative			Phone - Representative*			Emai	Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version	Manufacturing S	Site	Weight*	UOM	Unit Type	
	FGH401	FGH40T65SQD-F155 650V		50V 40A FS4 TRENCH IGBT		2024-04-27		CP8		5456.925	mg	Each	
Ianufacturing Proccess In	formation					-	-					·	
Terminal Plating / Grid Array Material Ter		erminal Base Alloy J-STD-020 MSL		L Rating	Peak Process Body Temperature Max		ature Max Time a	t Peak Tempe	erature Numb	er of Reflow Cy	cles		
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0	С	30	sec	conds 3			
omments													
or more information regarding r	naterial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier rinto a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	32.0	mg	Supplier	Silicon (Si)	7440-21-3		32	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			А	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
Lead Frame	3612.9	mg	Supplier	Iron (Fe)	7439-89-6		3.6129	mg
			Supplier	Copper (Cu)	7440-50-8		3608.2031	mg
			Supplier	Phosphorus (P)	7723-14-0		1.0839	mg
Mold Compound-Black	1740.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		130.5	mg
			Supplier	Carbon Black (C)	1333-86-4		8.7	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1522.5	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		78.3	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg